

Issue date: 13 Jun 2024

Effective date: 13 Jul 2024

Footprint adjustment for SOT1289B products and typo data sheet

Notification information

The distance between anode and cathode is changed from 0.6mm to 1.0mm to follow recommendation of IPC2221 for products >100V. This was achieved by reducing the anode pad size from 1.54mm to 1.34mm and cathode pad size from 5.06mm to 4.86mm. By introducing this footprint change, also the recommendation of the solder stencil (solder paste) is updated accordingly. Same change apply also for products with 100V or less for package conformity.

The datasheet of PMEG100V060ELPE, PMEG100V060ELPE-Q, PMEG100V100ELPE and PMEG100V100ELPE-Q has been updated to correct a typo in the datasheet regarding the Average forward current as a function of solder point temperature Tsp.

In this CIN data sheet drafts with typo correction are provided. These also contain the changed footprints and can be understood as an example of what all other data sheets with a changed footprint will look like. Data sheets with a new footprint will be available on the website when this CIN comes into force.

Why do we issue this notification?

To follow recommendation of IPC2221 and typo correction.

Change Category

[X] Errata

Details of this change

Identification of affected products

Product Identification does not change

Impact

No impact to the product's functionality anticipated

Data sheet revision

A new datasheet will be issued

Additional information

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Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact your distribution partner.

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